

## C1206C102F2TACTU

Aliases (C1206C102F2TAC7800) SMD Comm X8G HT150C, Ceramic, 1,000 pF, 1%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	25 mg
Shelf Life	78 Weeks
MSL	1

Dimensions		
Chip Size	1206	
L	3.2mm +/-0.2mm	
W	1.6mm +/-0.2mm	
т	1.1mm +/-0.10mm	
S	1.5mm MIN	
В	0.5mm +/-0.25mm	

## Packaging Specifications Packaging T&R, 180mm, Plastic Tape

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Packaging Quantity	2500

Specifications	
Capacitance	1,000 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	1%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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